

<b>TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT</b> (Under 37 CFR 1.97(b) or 1.97(c))				Docket No. DC5157PCT1	
In Re Application Of: <span style="float: right;">CHENG et. al</span>					
Application No. <b>10/565916</b>	Filing Date	Examiner	Customer No. 00137	Group Art Unit	Confirmation No.
Title: Process for Fabricating Electronic Components Using Liquid Injection Molding					
<div style="text-align: center;"> <p>Address to:</p> <p>Commissioner for Patents</p> <p>P.O. Box 1450</p> <p>Alexandria, VA 22313-1450</p> </div> <div style="text-align: center; margin-top: 10px;"> <p><b>37 CFR 1.97(b)</b></p> </div> <p>1. <input checked="" type="checkbox"/> The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.</p> <div style="text-align: center; margin-top: 20px;"> <p><b>37 CFR 1.97(c)</b></p> </div> <p>2. <input type="checkbox"/> The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:</p> <div style="margin-left: 40px; margin-top: 10px;"> <p><input type="checkbox"/> the statement specified in 37 CFR 1.97(e);</p> <p style="text-align: center; margin-top: 10px;"><b>OR</b></p> <p><input type="checkbox"/> the fee set forth in 37 CFR 1.17(p).</p> </div>					

<b>TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT</b> (Under 37 CFR 1.97(b) or 1.97(c))				Docket No. DC5157PCT1	
In Re Application: CHENG et. al					
Application No. <b>10/565918</b>	Filing Date	Examiner	Customer No. 00137	Group Art Unit	Confirmation No.
Title: Process for Fabricating Electronic Components Using Liquid Injection Molding					
<p style="text-align: center;"><b>Payment of Fee</b> (Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))</p> <p><input type="checkbox"/> A check in the amount of _____ is attached.</p> <p><input type="checkbox"/> The Director is hereby authorized to charge and credit Deposit Account No. 04-1520 as described below.</p> <p style="margin-left: 40px;"> <input type="checkbox"/> Charge the amount of \$ _____  <input type="checkbox"/> Credit any overpayment.  <input type="checkbox"/> Charge any additional fee required.         </p> <p><input type="checkbox"/> Payment by credit card. Form PTO-2038 is attached.</p> <p><b>WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.</b></p> <div style="display: flex; justify-content: space-between;"> <div style="width: 45%;"> <p style="text-align: center;"><b>Certificate of Transmission by Facsimile*</b></p> <div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;">             I certify that this document and authorization to charge deposit account is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. _____)           </div> <div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;">             _____ (Date)           </div> <div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;">             _____ Signature           </div> <div style="border: 1px solid black; padding: 5px;">             _____ Typed or Printed Name of Person Signing Certificate           </div> </div> <div style="width: 45%;"> <p style="text-align: center;"><b>Certificate of Mailing by First Class Mail</b></p> <div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;">             I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a) _____]           </div> <div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;">             _____ (Date)           </div> <div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;">             _____ Signature of Person Mailing Correspondence Christine M. Fitak           </div> <div style="border: 1px solid black; padding: 5px;">             _____ Typed or Printed Name of Person Mailing Certificate           </div> </div> </div> <p style="margin-top: 10px;">*This certificate may only be used if paying by deposit account.</p> <div style="display: flex; justify-content: space-between; margin-top: 10px;"> <div style="width: 45%;"> <p><i>Catherine Brown</i> _____ Signature</p> <p>Catherine Brown Reg. No. 44,565 989-496-1725 Senior IP Attorney Mail Number C01232 P.O. Box 994 2200 W. Salzburg Road Midland, MI 48686-0994 UNITED STATES OF AMERICA</p> </div> <div style="width: 45%;"> <p>Dated: Jan 24, 2006</p> <p>CustomerNumber 00137</p> </div> </div> <p>cc:</p>					

<b>INFORMATION DISCLOSURE CITATION</b> <i>(Use several sheets if necessary)</i>				Docket Number (Optional) <b>DC5157PCT1</b>		Application Number <b>10/565916</b>		
				Applicant(s) <b>TAMMY CHENG et al.</b>				
				Filing Date		Group Art Unit		
<b>U.S. PATENT DOCUMENTS</b>								
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
		4,293,479	06-Oct-1981	Hanada, et. al.	260	37		
		4,327,369	27-Apr-1982	Kaplan	357	72		
		4,663,397	05-May-1987	Morita, et. al.	525	398		
		4,778,860	18-Oct-1988	Morita	525	431		
		4,880,882	14-Nov-1989	Morita, et. al.	525	446		
<b>U.S. PATENT APPLICATION PUBLICATIONS</b>								
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
		2001/0040283 A1	15-Nov-2001	Konishi, et. al.	257	687		
<b>FOREIGN PATENT DOCUMENTS</b>								
	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
		WO 2003/041130 A2	20-Sep-2002	EP				
		WO 2000/047391 A1	17-Aug-2000	EP				
		EP 0 685 508 B1	06-May-1999	EP				
		EP 0 707 042 B1	11-Mar-1998	EP				
		JP 83834/03	25-Mar-2003	JP				
<b>OTHER DOCUMENTS</b> <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>								
		Harper, Charles A., Ed., "Packaging Assembly Process," Packaging and Interconnection Handbook, 2nd ed., pp. 6.66-6.77, McGraw-Hill, New York, 1997.						
		Kroschwitz, J., ed., "Electronic Materials," Kirk-Othmer Encyclopedia of Chemical Technology, 4th ed., vol. 9, pp.219-229, John Wiley & Sons, New York, 1994.						
<b>EXAMINER</b>				<b>DATE CONSIDERED</b>				
<b>EXAMINER:</b> Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								

<b>INFORMATION DISCLOSURE CITATION</b> <i>(Use several sheets if necessary)</i>	Docket Number (Optional) <b>DC5157PCCT1</b>	
	Application Number <b>10/565916</b>	
	Applicant(s) <b>TAMMY CHENG et al.</b>	
		Filing Date Group Art Unit

**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		5,387,624	07-Feb-1995	Morita, et. al.	523	220	
		5,492,945	20-Feb-1996	Morita, et. al.	523	212	
		5,691,401	25-Nov-1997	Morita, et. al.	523	435	
		5,933,713	03-Aug-1999	Farnworth	438	127	

**U.S. PATENT APPLICATION PUBLICATIONS**

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

**FOREIGN PATENT DOCUMENTS**

REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

**OTHER DOCUMENTS** *(Including Author, Title, Date, Pertinent Pages, Etc.)*

		Abstract, DE 19801657, July 29, 1999.
		Abstract, "The Lead Plastic Chip Carrier - its Reliability and Use." Brodsky, et. al., January 1, 1981.
		Hmiel, Andrew F., et. al., "A Novel Process for Protecting Wire Bonds from Sweep During Molding.", SEMICON West 2002 Technology Symposium.

<b>EXAMINER</b>	<b>DATE CONSIDERED</b>
-----------------	------------------------

**EXAMINER:** Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.